

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

July 17, 2003

Hideo KOBAYASHI, Shinichi SHINOHARA, Hironobu NISHIMURA, and Yukio
UTSUNOMIYA

For : METHOD AND APPARATUS FOR CURING ADHESIVE
BETWEEN SUBSTRATES, AND DISK SUBSTRATES BONDING
APPARATUS

Our Docket : SHX 340

Mail Stop: Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313

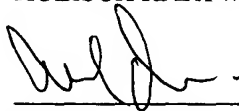
Sir:

CLAIM OF FOREIGN PRIORITY

Applicants hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below.

- 1. Japanese Patent Application Number: 2002-209897.**
Filed with the Japanese Patent Office on: July 18, 2002.
- 2. Japanese Patent Application Number: 2002-307283.**
Filed with the Japanese Patent Office on: October 22, 2002.
- 3. Japanese Patent Application Number: 2002-307385.**
Filed with the Japanese Patent Office on: October 22, 2002.
- 4. Japanese Patent Application Number: 2003-188734.**
Filed with the Japanese Patent Office on: June 30, 2003.

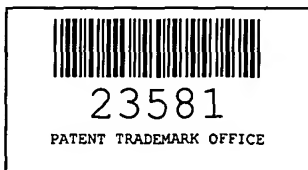
Respectfully submitted,
KOLISCH HARTWELL, P.C.



Mark D. Alleman
Registration No. 42,257
Of Attorneys/Agents for Applicants
Customer No. 23581
520 S.W. Yamhill Street, Suite 200
Portland, Oregon 97204
Telephone: (503) 224-6655
Facsimile: (503) 295-6679

July 17, 2003

Date of Mailing



MDA:gp
Enclosures